

HIP



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Multiscale model to approach the problem of electrical breakdown
Surface charge, workfunctions
Dislocations responsible for

surface response to electric fields
Dislocation based fit model



Summary







2

Evolution of a tip placed on Cu surface



F. Djurabekova, S. Parviainen, A. Pohjonen and K. Nordlund, PRE 83, 026704 (2011).

- Follow evolution of the surfaces by calculating the partial charge induced on metal surface atoms
- The dynamics of atom charges follows the shape of electric field distortion on tips on the surface
- Temperature on the surface tips is sufficient => atom evaporation enhanced by the field can supply neutrals to build up the plasma densities above surface.

DFT calculations to validate the charges on surface atoms



5

Two adatoms

ED-MD

-0.0177

DFT

-0.025

ED-MD

-0.0215



Workfunction near an adatom in Cu



> We have calculated the workfunction for Cu surface when a single adatom is present $\mathbf{F} = - E_F + W_s + DE_V$

	Cu(100)	Cu(110)	Cu(111)
Φ LDA [27]	4.898	4.708	5.170
$\Phi(\exp)$ [15]	4.599	4.490	4.980
Φ GGA (our calc.)	4.612	4.291	5.185





Motivations: why we look for dislocations?

The dislocation motion is strongly bound to the atomic structure of metals. In FCC (face-centered cubic) the dislocation are the most mobile and HCP (hexagonal close-packed) are the hardest for dislocation mobility.





Voids: the easy way to simulate a lattice violation





> We simulated a void near {110} Cu surface, when the high tensile stress is applied on the surface. Bottom is fixed, lateral boundary allowed to move in z direction.





A. Pohjonen, F. Djurabekova, et al., Dislocation nucleation from near surface void under static tensile stress on surface in Cu, *Jour. Appl. Phys.* 110, 023509 (2011).

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Finite Element Method calculations (ELMER)

0.362

We have calculated the distribution of shear stresses near the void The shear was applied perpendicular to the surface along plane XY



Stress.6

0.0146

0.768



0.0146

0.739

> We found a strong correlation between the maximum depth from where the void can still emit the dislocations within the MD timespan.

0.391

-0.362

-0.739

0.768



1

Concurrent ED-MD simulations of dislocations on a near-surface void

- Half-void of diameter 4nm in {110} Cu surface. (N of atoms» 170000 atoms...)
- E0=22 GV/m (exaggeration is required to simulate the dislocation within the MD time span)
- **>** T = 600 K





If the void has the company of a screw dislocation



A screw dislocation placed so that it intersects the void on a side, showed a cross-slip behavior leading to the atom step on the surface. This mechanism eventually combines with the previous mechanism, but to ignite this process less stress is required (in our simulations 1.7 GPa against 3 GPa).



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http://indico.cern.ch/conferenceDisplay.py?confld=8831.] with the model.] Flyura Djurabekova, HIP, University of Helsinki

Temperature dependence of BPP 10⁻³ **Experiment**, TD18 **Experimental data** > **Experiment**, T18 Fit of model on dependence of 10⁻⁴ Breakdown rate (1/pulse/m) Fit of model breakdown rate on the peak temperature 10⁻⁵ increase in accelerating 10⁻⁶ components 10⁻⁷ 30 40 50 60 90 80 20 70 Peak Pulse Heating at Last Cell (K) ast Cell (K) $R_{BD} = a \mathcal{C}_0 \exp \frac{\mathcal{E}^f + \mathcal{C}_0 E^2 DV}{\mathbf{c}} \ddot{\mathbf{c}} \frac{\mathbf{E}^f + \mathcal{C}_0 E^2 DV}{\mathbf{c}} \ddot{\mathbf{c}} \frac{\dot{\mathbf{c}}}{\mathbf{c}} \frac{\mathbf{E}^f + \mathcal{C}_0 E^2 DV}{\mathbf{c}} \ddot{\mathbf{c}} \frac{\dot{\mathbf{c}}}{\mathbf{c}} \frac{\mathbf{c}}{\mathbf{c}} \frac{\mathbf{c}}{$



From tips to plasma: From FE to discharge currents

Up to 12 orders of magnitude difference

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difference

 In real life we can observe the full dynamic range of a vacuum discharge:

- ø > 10s pA in 'weak' FE phase
- ø Space charge limited 'strong' FE phase, typically ~ nA μ A
- Ø Discharge current, up to 10 100 A
- At the same time, the involved area changes:
 - **g** Typically $10^{-20} 10^{-14}$ m² for weak FE Þ R_{em} ~ 0.1 100 nm
 - **\boldsymbol{\varnothing}** During the discharge, the bombarded area has R ~ 10 100





Slide courtesy of Helga Timko



They provide us with a link between

1. Micro- & macroscopic surface processes:

Triggering (nano-scale) ® plasma ® crater formation

 Theory & experiments: Using reasonable physical assumptions (theory), to predict the evolution of measurable quantities (experiment)

H. Timko, K. Matyash, R. Schneider, F. Djurabekova, K. Nordlund, A. Hansen, A. Descoeudres, J. Kovermann, A. Grudiev, W. Wuensch, S. Calatroni, and M. Taborelli , *Contrib. Plasma Phys. 5*1, 5-21 (2011)











- > We develop a multiscale model, which comprises the different physical processes (nature and time wise) probable right before, during and after an electrical breakdown event:
 - **ø** All the parts of the general model are pursued in parallel. We develop intense activities to cover all possible aspects.
- > Our modeling shows:
 - ø Plasma is fed from the tips grown under the high electric field
 - **ø** Tip growth can be explained by the relaxation of stresses inside of a material by the dislocation motion
 - A dislocation-mediated mechanism can explain the high slopes of breakdown rates against the accelerating fields

RRENT PROJECTS

N COLLISON

ONO COLLISION

A GLUONE DECECTION COLLISION





ADVANCED PARTICAL COLLIDER